

ZXTC6720MC

DUAL 80V NPN & 70V PNP LOW SATURATION TRANSISTOR COMBINATION

Features and Benefits

NPN Transistor

- $BV_{CEO} > 80V$
- $I_C = 3.5A$ Continuous Collector Current
- Low Saturation Voltage (185mV max @ 1A)
- $R_{SAT} = 68m\Omega$ for a low equivalent On-Resistance

PNP Transistor

- $BV_{CEO} > -70V$
- $I_C = -2.5A$ Continuous Collector Current
- Low Saturation Voltage (-220mV max @ -1A)
- $R_{SAT} = 117m\Omega$ for a low equivalent On-Resistance
- h_{FE} characterized up to -5A for high current gain hold up
- Low profile 0.8mm high package for thin applications
- $R_{\theta JA}$ efficient, 40% lower than SOT26
- 6mm² footprint, 50% smaller than TSOP6 and SOT26
- **Lead-Free, RoHS Compliant (Note 1)**
- **Halogen and Antimony Free. "Green" Device (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

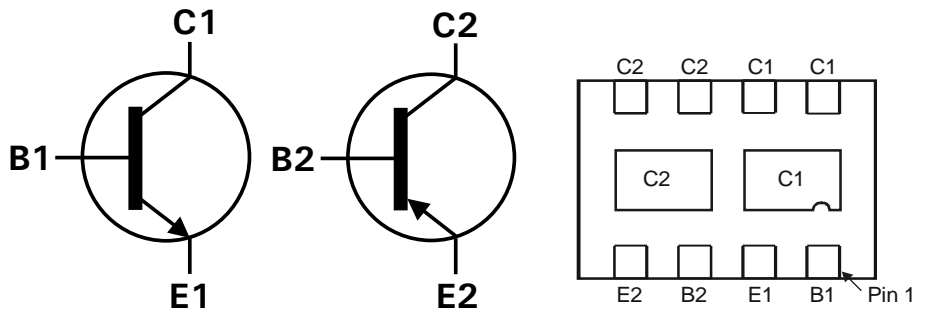
Mechanical Data

- Case: DFN3020B-8
- Case Material: Molded Plastic. "Green" Molding Compound.
- Terminals: Pre-Plated NiPdAu leadframe.
- Nominal package height: 0.8mm
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Weight: 0.013 grams (approximate)

Applications

- DC – DC Converters
- Charging circuits
- Power switches
- Motor control
- Portable applications

DFN3020B-8



Top View

Bottom View

NPN Transistor

PNP Transistor

Bottom View
Pin Out

Equivalent Circuit

Ordering Information (Note 3)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTC6720MCTA	DE4	7	8	3,000

- Notes:
1. No purposefully added lead.
 2. Diodes Inc's "Green" Policy can be found on our website at <http://www.diodes.com>
 3. For Packaging Details, go to our website at <http://www.diodes.com>.

Marking Information



DE4 = Product type marking code
Top View, Dot Denotes Pin 1

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

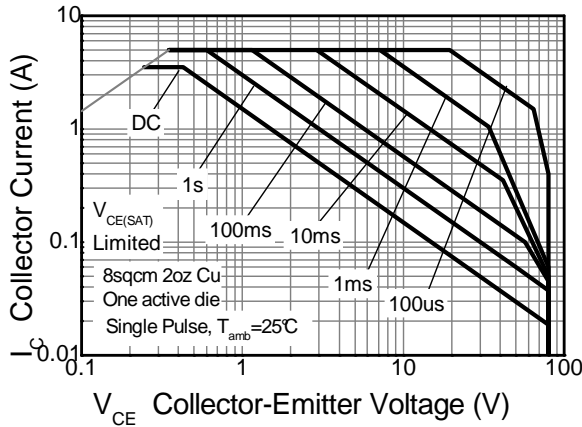
Parameter		Symbol	NPN	PNP	Unit
Collector-Base Voltage		V_{CBO}	100	-70	V
Collector-Emitter Voltage		V_{CEO}	80	-70	
Emitter-Base Voltage		V_{EBO}	7	-7	
Peak Pulse Current		I_{CM}	5	-3	A
Continuous Collector Current	(Notes 4 & 7)	I_C	3.5	-2.5	
	(Notes 5 & 7)		4	-3	
Base Current		I_B	1		

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

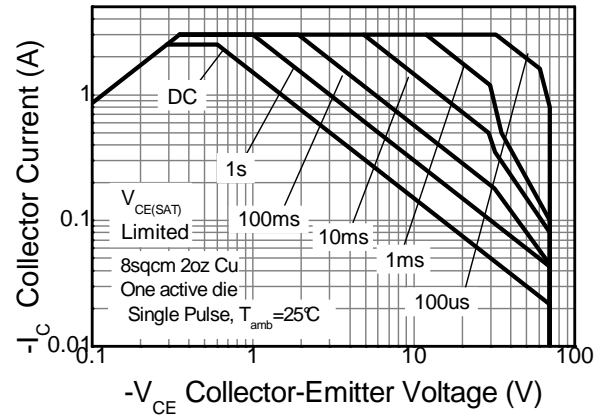
Characteristic		Symbol	NPN	PNP	Unit
Power Dissipation Linear Derating Factor	(Notes 4 & 7)	P_D	1.5 12		W mW/°C
	(Notes 5 & 7)		2.45 19.6		
	(Notes 6 & 7)		1.13 8		
	(Notes 6 & 8)		1.7 13.6		
Thermal Resistance, Junction to Ambient	(Notes 4 & 7)	$R_{\theta JA}$	83.3		°C/W
	(Notes 5 & 7)		51.0		
	(Notes 6 & 7)		111		
	(Notes 6 & 8)		73.5		
Thermal Resistance, Junction to Lead	(Notes 7 & 9)	$R_{\theta JL}$	17.1		
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150		°C

- Notes:
4. For a dual device surface mounted on 28mm x 28mm (8cm²) FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions; the device is measured when operating in a steady-state condition. The heatsink is split in half with the exposed collector pads connected to each half.
 5. Same as note (4), except the device is measured at $t < 5$ sec.
 6. Same as note (4), except the device is surface mounted on 31mm x 31mm (10cm²) FR4 PCB with high coverage of single sided 1oz copper.
 7. For a dual device with one active die.
 8. For dual device with 2 active die running at equal power.
 9. Thermal resistance from junction to solder-point (at the end of the collector lead).

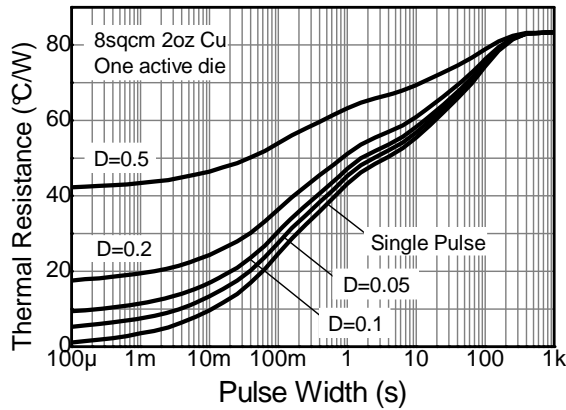
Thermal Characteristics



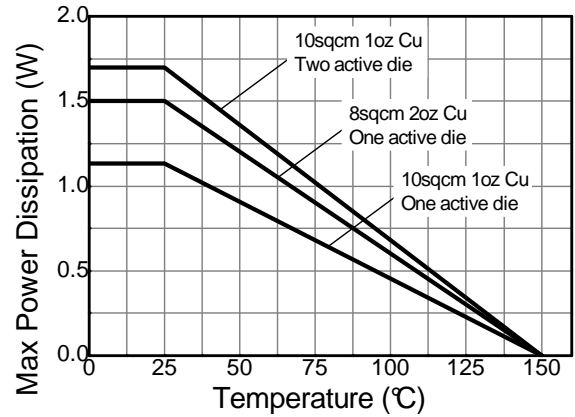
NPN Safe Operating Area



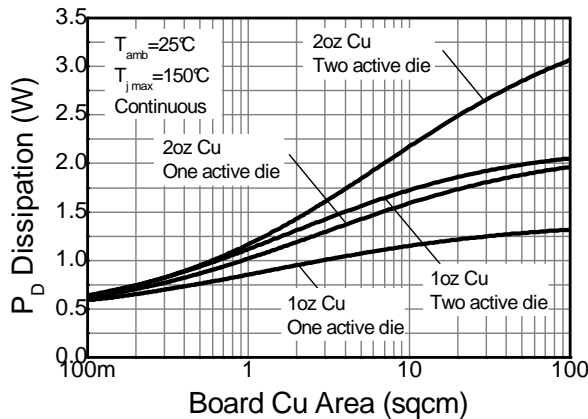
PNP Safe Operating Area



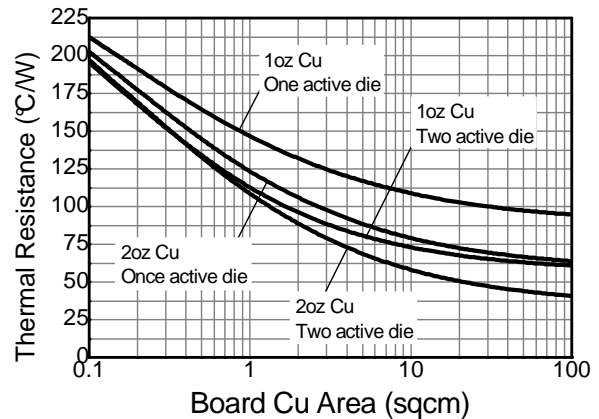
Transient Thermal Impedance



Derating Curve



Power Dissipation v Board Area



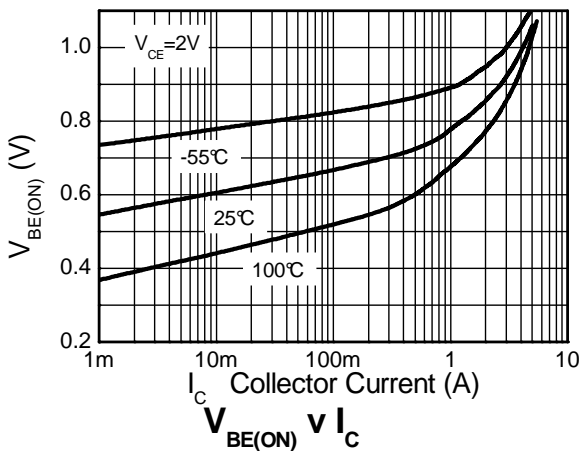
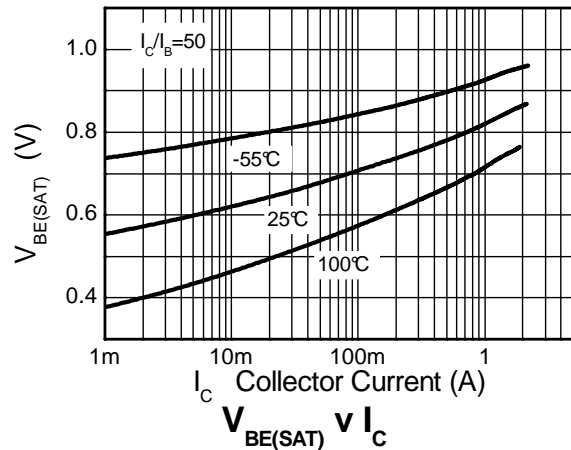
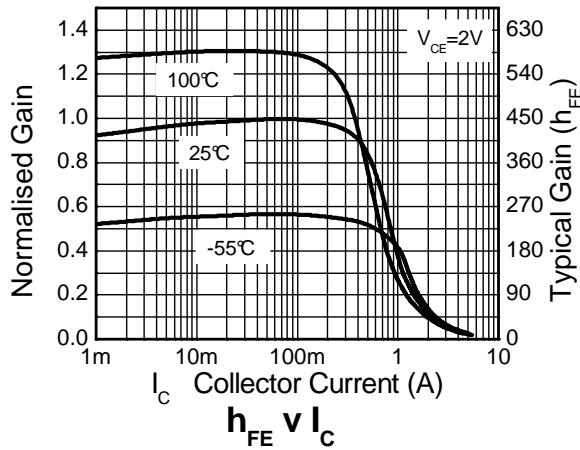
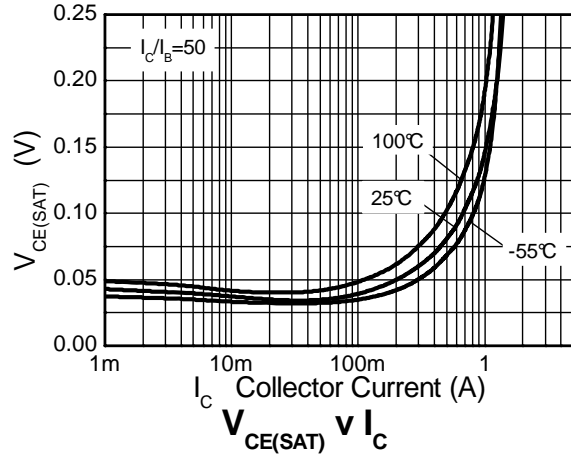
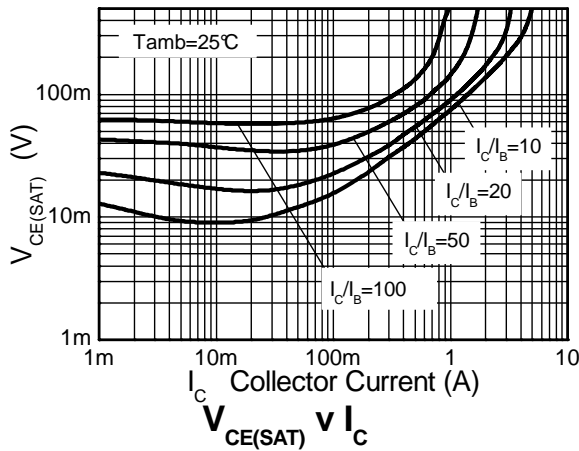
Thermal Resistance v Board Area

Electrical Characteristics, NPN Transistor (at $T_A = 25^\circ\text{C}$ unless otherwise specified)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	100	180	-	V	$I_C = 100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 10)	BV_{CEO}	80	110	-	V	$I_C = 10\text{mA}$
Emitter-Base Breakdown Voltage	BV_{EBO}	7	8.2	-	V	$I_E = 100\mu\text{A}$
Collector Cutoff Current	I_{CBO}	-	-	100	nA	$V_{CB} = 80\text{V}$
Emitter Cutoff Current	I_{EBO}	-	-	100	nA	$V_{EB} = 6\text{V}$
Collector Emitter Cutoff Current	I_{CES}	-	-	100	nA	$V_{CE} = 65\text{V}$
Static Forward Current Transfer Ratio (Note 10)	h_{FE}	200	450	-	-	$I_C = 10\text{mA}, V_{CE} = 2\text{V}$
		300	450	900		$I_C = 200\text{mA}, V_{CE} = 2\text{V}$
		110	170	-		$I_C = 1\text{A}, V_{CE} = 2\text{V}$
		60	90	-		$I_C = 1.5\text{A}, V_{CE} = 2\text{V}$
		20	30	-		$I_C = 3\text{A}, V_{CE} = 2\text{V}$
-	10	-	$I_C = 5\text{A}, V_{CE} = 2\text{V}$			
Collector-Emitter Saturation Voltage (Note 10)	$V_{CE(sat)}$	-	15	20	mV	$I_C = 0.1\text{A}, I_B = 10\text{mA}$
		-	45	60		$I_C = 0.5\text{A}, I_B = 50\text{mA}$
		-	145	185		$I_C = 1\text{A}, I_B = 20\text{mA}$
		-	160	200		$I_C = 1.5\text{A}, I_B = 50\text{mA}$
		-	240	340		$I_C = 3.5\text{A}, I_B = 300\text{mA}$
Base-Emitter Turn-On Voltage (Note 10)	$V_{BE(on)}$	-	0.96	1.05	V	$I_C = 3.5\text{A}, V_{CE} = 2\text{V}$
Base-Emitter Saturation Voltage (Note 10)	$V_{BE(sat)}$	-	1.09	1.175	V	$I_C = 3.5\text{A}, I_B = 300\text{mA}$
Output Capacitance	C_{obo}	-	11.5	18	pF	$V_{CB} = 10\text{V}, f = 1\text{MHz}$
Transition Frequency	f_T	100	160	-	MHz	$V_{CE} = 10\text{V}, I_C = 50\text{mA}, f = 100\text{MHz}$
Turn-on Time	t_{on}	-	86	-	ns	$V_{CC} = 10\text{V}, I_C = 1\text{A}$
Turn-off Time	t_{off}	-	1128	-	ns	$I_{B1} = I_{B2} = 25\text{mA}$

Notes: 10. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

NPN - Typical Electrical Characteristics

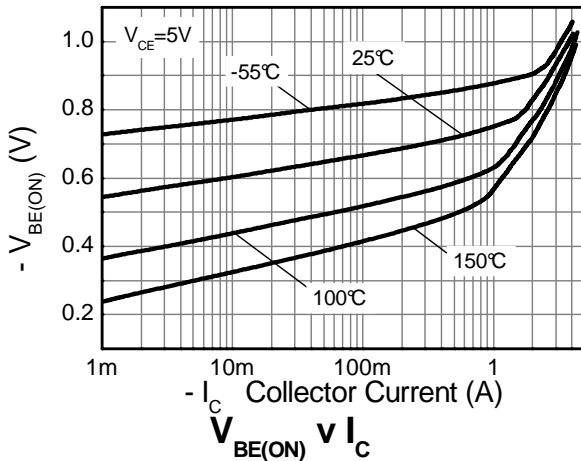
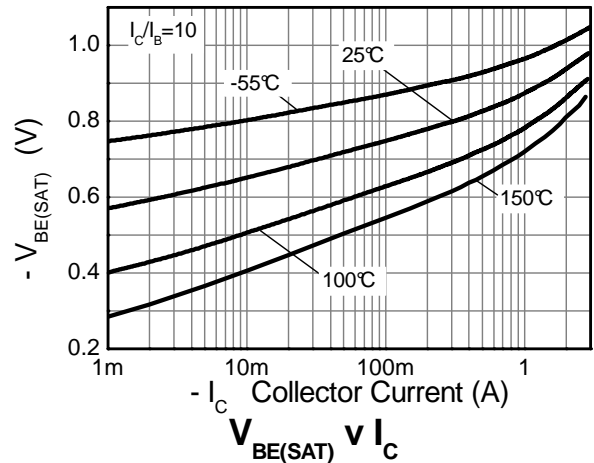
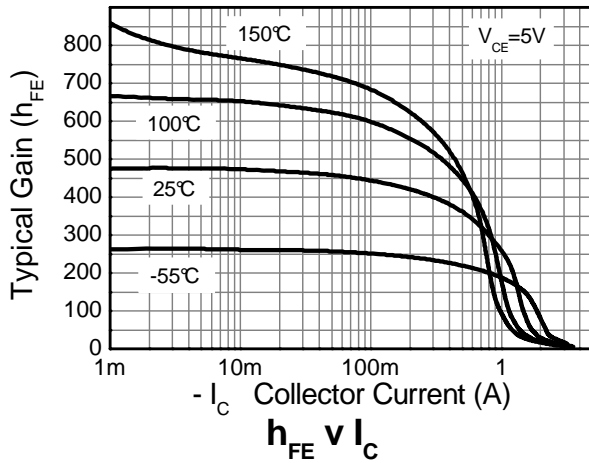
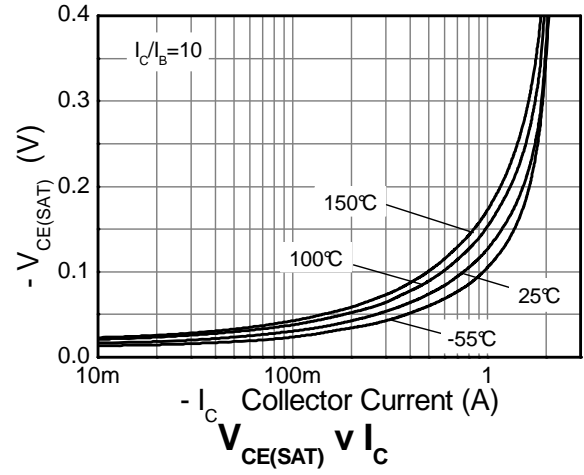
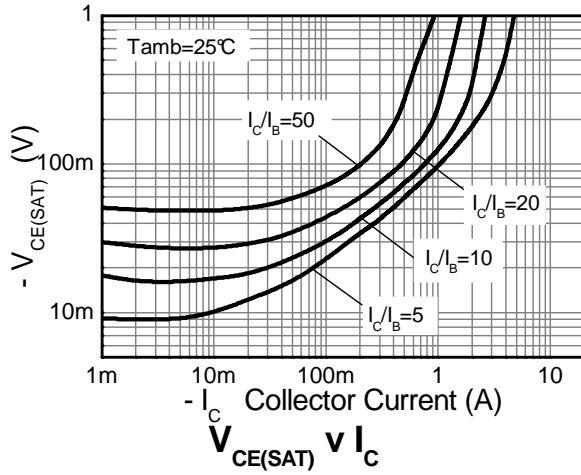


PNP - Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-70	-150	-	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 11)	V _{(BR)CEO}	-70	-125	-	V	I _C = -10mA
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	-7	-8.5	-	V	I _E = -100μA
Collector Cutoff Current	I _{CBO}	-	-	-100	nA	V _{CB} = -55V
Emitter Cutoff Current	I _{EBO}	-	-	-100	nA	V _{EB} = -6V
Collector Emitter Cutoff Current	I _{CES}	-	-	-100	nA	V _{CE} = -55V
Static Forward Current Transfer Ratio (Note 11)	h _{FE}	200	470	-	-	I _C = -10mA, V _{CE} = -5V
		300	450	-		I _C = -100mA, V _{CE} = -5V
		175	275	-		I _C = -1A, V _{CE} = -5V
		40	60	-		I _C = -1.5A, V _{CE} = -5V
		-	10	-		I _C = -3A, V _{CE} = -5V
Collector-Emitter Saturation Voltage (Note 11)	V _{CE(sat)}	-	-35	-50	mV	I _C = -0.1A, I _B = -10mA
		-	-135	-200		I _C = -0.5A, I _B = -20mA
		-	-140	-220		I _C = -1.0A, I _B = -100mA
		-	-175	-270		I _C = -1.5A, I _B = -200mA
Base-Emitter Turn-On Voltage (Note 11)	V _{BE(on)}	-	0.78	1.00	V	I _C = -1.5A, V _{CE} = -5V
Base-Emitter Saturation Voltage (Note 11)	V _{BE(sat)}	-	0.94	1.05	V	I _C = -1.5A, I _B = -200mA
Output Capacitance	C _{obo}	-	14	20	pF	V _{CB} = -10V, f = 1MHz
Transition Frequency	f _T	150	180	-	MHz	V _{CE} = -10V, I _C = -50mA, f = 100MHz
Turn-on Time	t _{on}	-	40	-	ns	V _{CC} = -50V, I _C = -1A
Turn-off Time	t _{off}	-	700	-	ns	I _{B1} = I _{B2} = -50mA

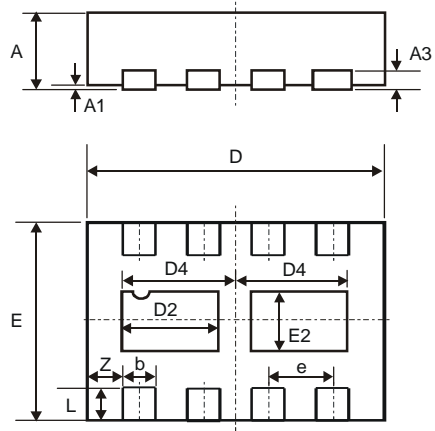
Notes: 11. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

PNP - Typical Electrical Characteristics



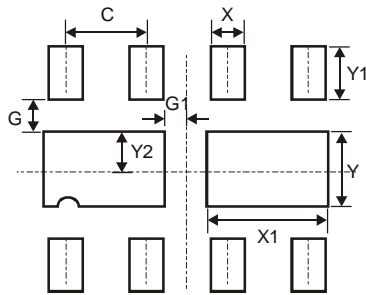
ZXTC6720MC

Package Outline Dimensions



DFN3020B-8			
Dim	Min	Max	Typ
A	0.77	0.83	0.80
A1	0	0.05	0.02
A3	-	-	0.15
b	0.25	0.35	0.30
D	2.95	3.075	3.00
D2	0.82	1.02	0.92
D4	1.01	1.21	1.11
e	-	-	0.65
E	1.95	2.075	2.00
E2	0.43	0.63	0.53
L	0.25	0.35	0.30
Z	-	-	0.375
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
C	0.650
G	0.285
G1	0.090
X	0.400
X1	1.120
Y	0.730
Y1	0.500
Y2	0.365

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